

# Product / Process Change Notification



N° 2018-126-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

## Change of the assembly location from AMKOR, Korea to ASE, Taiwan and update of the data sheet affecting dedicated products in package BGA 516

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **25. July 2019**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:  
**"Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."**

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG  
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Chairman of the Supervisory Board: Dr. Eckart Süner  
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider  
Registered Office: Neubiberg  
Commercial Register: München HRB 126492

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► **Products affected:** Please refer to attached affected product list 1\_cip18126\_a

► **Detailed Change Information:**

**Subject:** Change of the assembly location from AMKOR, Korea to ASE, Taiwan and update of the data sheet affecting the products TC299TP, TC299T & TC299TC in package BGA 516

**Reason:** Harmonization of the production site strategy affecting Infineon's AURIX™ product family.

<b>Description:</b>	<u>Old</u>	<u>New</u>
<b>Assembly location:</b>	■ Amkor (plant ATK4), Korea	■ ASE (plant K5), Taiwan
<b>Die attach material:</b>	■ Glue ,ABLEBOND 2300'	■ Glue ,ABLEBOND 2100A'
<b>Sales part number:</b>	SP001662172 SP001604770 SP001207664 SP001366090 SP001397596 SP001260190	SP005349253 SP005349254 SP005349255 SP005349256 SP005349257 SP005349258
<b>Data sheet update:</b>	■ Rev. 1.1 (TC29xB) Rev. 1.0 (TC29xBC)	■ Rev. 1.2 (TC29xB) Rev. 1.1 (TC29xBC) (for details refer to 4_cip18126_a attached)
<b>Substrate supplier:</b>	■ KCC	■ UMTC

► **Product Identification:** The traceability is ensured by

- lot number
- Infineon sales part number

► **Impact of Change:** No change in form, fit or function.

For Automotive products only: DeQuMa-ID: SEM-DS-02; SEM-PA-07;  
SEM-PA-18; SEM-PA-16

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## ► Attachments:

Affected product list 1\_cip18126\_a  
Data sheet(s) 4\_cip18126\_a

## ► Time Schedule:

- |                               |                      |
|-------------------------------|----------------------|
| ■ Final qualification report: | Available on demand  |
| ■ First samples available:    | Available on request |
| ■ Intended start of delivery: | October 2019         |

If you have any questions, please do not hesitate to contact your local Sales office.

**PCN N°2018-126-A**

Change of the assembly location from AMKOR, Korea to ASE, Taiwan and update of the data sheet affecting dedicated products in package BGA 516



<b>Sales Name</b>	<b>SP number</b>	<b>OPN</b>	<b>Package</b>
SAK-TC299T-128F300S BC	SP001662172	TC299T128F300SBCKXUMA1	PG-LFBGA-516
SAK-TC299TP-128F300N BC	SP001604770	TC299TP128F300NBCKXUMA1	PG-LFBGA-516
SAK-TC299TP-128F300S BB	SP001207664	TC299TP128F300SBBKXUMA1	PG-LFBGA-516
SAK-TC299TP-128F300S BC	SP001366090	TC299TP128F300SBCKXUMA1	PG-LFBGA-516
SAL-TC299TP-128F300N BC	SP001397596	TC299TP128F300NBCLXUMA1	PG-LFBGA-516
SAL-TC299TP-128F300S BB	SP001260190	TC299TP128F300SBBLXUMA1	PG-LFBGA-516